

SURFACE-MOUNT MULTI-LAYER CHIP BEADS

FEATURES:

- Multilayer structure
- Closed magnetic circuit
- Avoids crosstalk
- Excellent magnetic shield
- Excellent solderability
- High reliability
- EMI/RFI suppression
- 20% impedance tolerance

COMMON APPLICATIONS:

- Cellular Phones
- Mobil Radios
- Cordless Telephones
- Modems
- Global Positioning Systems
- Wireless Communications Equipment
- Network Systems
- Computer Products

ELECTRICAL CHARACTERISTICS :

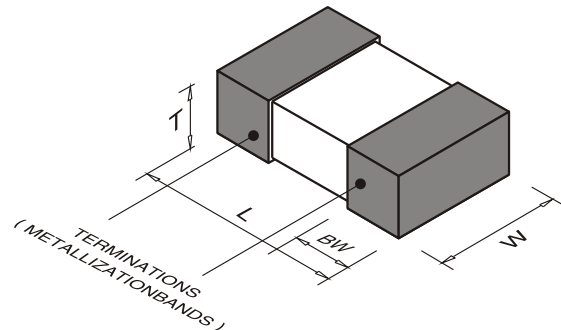
IMPEDANCE (Ω) AT 100 MHz	DCR (Ω) Max	IDC Max mA
5	0.05	1000
9	0.05	1000
11	0.05	1000
19	0.05	1000
26	0.06	500
31	0.06	500
60	0.12	300
70	0.12	300
80	0.12	300
100	0.20	200
120	0.20	200
150	0.20	200
180	0.30	200
220	0.30	200
300	0.35	150
500	0.40	150
600	0.45	100
800	0.50	100
1000	0.60	100
1200	0.80	100
1500	0.90	50
2000	1.20	50

Note: 1. K = $\pm 10\%$, M = $\pm 20\%$

TECHNICAL INFORMATION PHYSICAL CHARACTERISTICS

- Testing: Impedance vs. Frequency: HP 4195A
- Solderability: 90% of the terminal electrode shall be covered
Preheat: @ 260°C \pm 5°C for 60 seconds
Flux: Rosin, Dip for 10 seconds \pm 1 second
- Thermal Shock: Impedance shall be within $\pm 20\%$ of initial value when temperature is -25°C and +85°C for 30 minutes for each 50 cycles
- Operating Temperature: -25°C to +85°C
- Storage Temperature: -25°C to +85°C

(Refer to Size Chart Page 4)



Note: All specifications subject to change without notice.

TERMINATIONS (METALLIZATION BANDS)